

Amendments to the claims:

This listing of claims will replace all prior versions and listing, of claims in the application:

Listing of Claims:

Claim 1 (original): A method for mounting an electronic part on a mounting substrate in that projection electrodes provided on said electronic part are welded by fusion to join connection terminals provided on said mounting substrate, said mounting method comprising the steps of:

arranging a flux paste on said mounting substrate, said flux paste including a base flux and metal grains having diameters smaller than diameters of said projection electrodes and having a thickness so as to form a space between said flux paste and said electronic part when said electronic part is mounted on said mounting substrate; and

sealing a resin in the space formed between said electronic part and said mounting substrate after said projection electrodes are joined to said connection terminals.

Claim 2 (original): The method as claimed in claim 1, wherein the diameters of said metal grains are defined to be more than a tolerance of diameters of said projection electrodes and less than one third the diameter of said projection electrodes, and

said flux paste includes said metal grains more than one percent and less than twenty percent by volume ratio.

Claim 3 (original): The method as claimed in claim 1, wherein said flux paste is arranged on an area having said connection terminals of said mounting substrate by a thickness being more than the diameters of said metal grains and less than half the diameters of said projection electrodes.

Claim 4 (original): The method as claimed in claim 1, wherein a base flux of said flux paste includes a resin used to seal the space as a main constituent.

Claim 5 (original): The method as claimed in claim 1, wherein a base flux of said flux paste includes a resin, which is used to seal the space and filler is eliminated from, as a main constituent.

Claim 6 (original): The method as claimed in claim 1, wherein:
said projection electrodes have a spherical shape, and
said metal grains have a shape having a smooth surface so as to be movable when said projection electrodes are pressed to said connection terminals.

Claim 7 (original): A method for mounting an electronic part on a mounting substrate in that projection electrodes provided on said electronic part are welded by fusion to join connection terminals provided on said mounting substrate, said mounting method

comprising the steps of:

arranging a flux paste on said projection electrodes, said flux paste including metal grains having diameters smaller than diameters of said projection electrodes and having a thickness so as to form a space between said electronic part and said flux paste when said electronic part is mounted on said mounting substrate;

joining said projection electrodes to said connection part by mounting said electronic part on said mounting substrate and conducting a heating process; and

sealing a resin in said space formed between said electronic part and said mounting substrate after said projection electrodes are joined to said connection terminals.

Claim 8 (original): The method as claimed in claim 7, wherein the diameters of said metal grains are defined to be more than a tolerance of the diameters of said projection electrodes and less than one third the diameter of said projection electrodes, and

said flux paste includes said metal grains more than one percent and less than twenty percent by volume ratio.

Claim 9 (original): The method as claimed in claim 7, wherein a base flux of said flux paste includes a resin used to seal the space as a main constituent.

Claim 10 (original): The method as claimed in claim 7, wherein a base flux of said

flux paste includes a resin, which is used to seal the space and filler is eliminated from, as a main constituent.

Claim 11 (original): The method as claimed in claim 7,
wherein:
said projection electrodes have a spherical shape, and
said metal grains have a shape having a smooth surface so as to be capable of being
pushed outward when said projection electrodes are pressed to said connection terminals.

Claim 12 (canceled).